

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7156104

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
PAUL DANNA	01/27/2022
VINCENT W. MICHNA	01/28/2022
CHI KIM SIDES	01/27/2022
RECEIVING PARTY DATA	
Name:	HEWLETT PACKARD ENTERPRISE DEVELOPMENT LP
Street Address:	11445 COMPAQ CENTER DR W
City:	HOUSTON
State/Country:	TEXAS
Postal Code:	77070
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17587818
CORRESPONDENCE DATA	
Fax Number:	(530)204-4064
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	530-746-7839
Email:	admin@yaolegal.com
Correspondent Name:	SHUN YAO
Address Line 1:	YAO LEGAL SERVICES, INC.
Address Line 2:	2800 FIFTH STREET, SUITE 110
Address Line 4:	DAVIS, CALIFORNIA 95618
ATTORNEY DOCKET NUMBER:	90968884
NAME OF SUBMITTER:	SHUN YAO
SIGNATURE:	/Shun Yao, Reg.# 59242/
DATE SIGNED:	02/02/2022
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
source=90968884_Declaration#page1.tif	
source=90968884_Declaration#page2.tif	

Record ID: 90968884

**COMBINED DECLARATION AND ASSIGNMENT
FOR UTILITY AND DESIGN PATENT APPLICATION****Title of
Application**

DUAL-PATH HIGH-SPEED INTERCONNECT PCB LAYOUT SOLUTION

Filing Date: 28 January 2022**Application No.:** 17/587,818**DECLARATION**

As a below named inventor, I hereby declare that:

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

In this Assignment, the "Patent Items" include the above-identified application for Patent and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Patent, and any and all other Patent(s) of any countries thereto which may be granted thereon or therefore, and any reissues, or reexaminations, or extensions of said Patent(s).

I/We, the undersigned (each):

hereby confirm the assignment and transfer of the entire right, title and interest, including the right of priority, in, to and under the Patent Items to HPED by virtue of a previously executed agreement,

acknowledge that I/we have previously agreed to assign and transfer to HPED the entire right, title and interest, including the right of priority, in, to and under the Patent Items, and

to the extent not already effected by a previously executed agreement, for good and valuable consideration, the receipt of which is hereby acknowledged, and in furtherance of my/our obligations to Hewlett Packard Enterprise Development LP, a Texas Limited Partnership having its principal place of business in Houston, Texas, (hereinafter HPED), and to its subsidiaries and affiliates, hereby assign and transfer to HPED, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under the Patent Items.

I/we additionally authorize HPED to file applications in my/our name for Patent in any country, to be held and enjoyed by HPED, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment and transfer not been made;

AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said Patent Items, to HPED, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPED, or to its nominee, all known facts respecting said invention(s) or improvement(s), said Patent Items, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPED, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPED;

AND I/we hereby authorize and request the official of any country or countries whose duty it is to issue patents on applications as aforesaid, to issue to HPED, as assignee of the entire right, title and interest, any and all Patent(s) for said invention(s) or improvement(s) which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

PATENT APPLICATION

Record ID: 90968884

I/we further authorize and direct the attorneys of record to insert the filing date and application number of said application for Patent, now identified by the Record ID and title set forth above, as soon as the same shall have been made known to them.

IN WITNESS WHEREOF, I/we hereunto set my/our hand(s) and seal(s):

/ Paul Danna
Inventor's Signature

/ January 27, 2022

Date

Paul Danna

First/Middle Name/Last Name

/ Vincent W. Michna
Inventor's Signature

/ January 28, 2022

Date

Vincent W. Michna

First/Middle Name/Last Name

/ Chi Kim Sides
Inventor's Signature

/ January 27, 2022

Date

Chi Kim Sides

First/Middle Name/Last Name